Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.
NOTES:
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-006/TO-100.
EXAMPLE BOARD LAYOUT

TO-CAN - 5.72 mm max height

METAL CYLINDRICAL PACKAGE

LAND PATTERN EXAMPLE
NON-SOLDER MASK DEFINED
SCALE: 12X
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